

# **4-Lane DisplayPort™ Rev 1.2 Compliant Switch**

#### **Features**

- → 4-lane, 1:2 mux/demux that will support RBR, HBR1, or HBR2
- → 1-channel 1:2 mux/demux for DP\_HPD signal
- → 1-differential channel 1:2 mux/demux for DP\_Aux signal with support up to 720Mbps
- → -1.6dB Insertion Loss for Dx channels @ 2.7 GHz (TQFN)
- → -3dB Bandwidth for Dx channels: 4.6GHz (TQFN)
- → Return loss for Dx channels @ 2.7GHz: -16dB (TQFN)
- → Low Bit-to-Bit Skew, 5ps typ (between '+' and '-' bits)
- → Low Crosstalk for high speed channels: -28dB@5.4 Gbps
- → Low Off Isolation for high speed channels: -22dB@5.4 Gbps
- → V<sub>DD</sub> Operating Range: 3.3V +/-10%
- → ESD Tolerance: 2kV HBM
- → Low channel-to-channel skew, 35ps max
- → Packaging (Pb-free & Green):
  - 42 TQFN (ZHE)
  - □ 48 BGA (NEE)

### Description

Pericom Semiconductor's PI3VDP12412 mux/demux is targeted for next generation digital video signals. This device can be used to connect a DisplayPort™ Source to two Independent DisplayPort Sinks or to connect two DisplayPort sources to a single DP display.

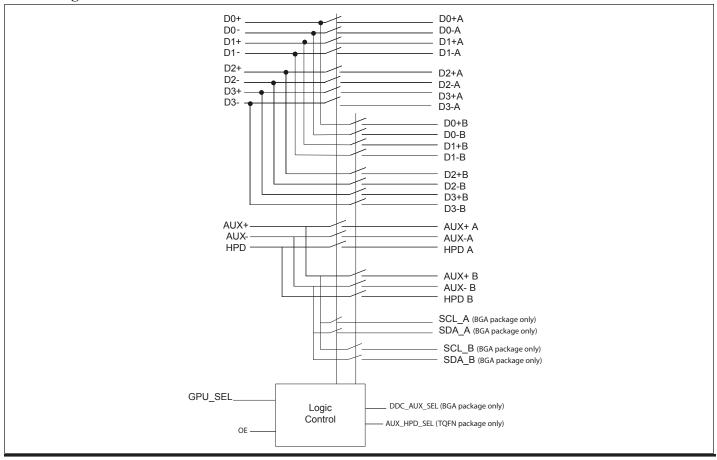
PI3VDP12412 supports DisplayPort 1.2 which requires a data rate of 5.4 Gbps. PI3VDP12412 offers excellent signal integrity at this high data rate with very low insertion loss, good return loss, and very small crosstalk.

PI3VDP12412 is available in two package types, a 5 mm x 5 mm 48 BGA and a 3.5 mm x 9 mm 42 TQFN. The BGA consumes less board space. The TQFN achieves slightly better signal integrity.

### **Application**

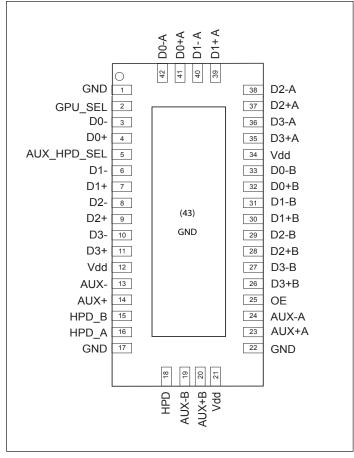
Routing of DisplayPort signals with low signal attenuation between source and sink.

### **Block Diagram**





Pin Assignment (TQFN-42, ZHE)



Truth Table for 42 pin package

OE	GPU_ SEL	AUX_ HPD_ SEL	Function
High	Low	Low	Port A active for all channels
High	Low	High	Port A for HS, port B for HPD/AUX
High	High	Low	Port B for HS, port A for HPD/AUX
High	High	High	Port B active for all channels
Low	X	x	All I/O's are hi-z and IC is power down

### Pin Assignment (48-Ball BGA, NEE)

	1	2	3	4	5	6	7	8	9
А	GPU_SEL	Vdd		D0-A	D1-A	D2-A		D3+A	D3-A
В	D0-	D0+	GND	D0+A	D1+A	D2+A	OE	D0+B	D0-B
С		DDC_ AUX_ SEL						GND	
D	D1-	D1+						D1+B	D1-B
E	D2-	D2+						D2+B	D2-B
F	D3-	D3+						D3+B	D3-B
G		GND						GND	
Н	AUX-	AUX+	HPD_B	GND	SCL_B	AUX+B	GND	SCL_A	AUX+A
J	HPD	HPD_A		Vdd	SDA_B	AUX-B		SDA_A	AUX-A

OE	GPU_ SEL	DDC_ AUX_ SEL	Function
High	Low	Low	Port A active for AUX, HPD & HS channel
High	Low	High	Port A active for DDC, HPD, & HS channel
High	High	Low	Port B active for AUX, HPD & HS channel
High	High	High	Port B active for DDC, HPD & HS channel
Low	x	x	all I/Os are hi-z and IC is power down



42ZHE pin#	48NEE pin#	pin Name	Signal Type	Description
	1	1	0 71	switch logic control. different function for different package options:
				42pin TQFN package: If HIGH, then path B is selected for high speed channels only If LOW, then path A is selected for high speed channels only
2	A1	GPU_SEL	I	
				48ball BGA package:
				If HIGH, then path B is selected for all channels If LOW, then path A is selected for all channels
3	B1	D0-	I/O	negative differential signal 0 for COM port
4	B2	D0+	I/O	positive differential signal 0 for COM port
6	D1	D1-	I/O	negative differential signal 1 for COM port
7	D2	D1+	I/O	positive differential signal 1 for COM port
8	E1	D2-	I/O	negative differential signal 2 for COM port
9	E2	D2+	I/O	positive differential signal 2 for COM port
10	F1	D3-	I/O	negative differential signal 3 for COM port
11	F2	D3+	I/O	positive differential signal 3 for COM port
1	В3	GND	Ground	Ground
13	H1	AUX-	I/O	negative differential signal for AUX COM port
14	H2	AUX+	I/O	positive differential signal for AUX COM port
18	J1	HPD	I/O	HPD for COM port
16	J2	HPD_A	I/O	HPD for port A
15	Н3	HPD_B	I/O	HPD for port B
17	C8	GND	Ground	Ground
12	J4	VDD	Pwr	3.3V +/-10% power supply
	G2	GND	Ground	Ground
20	Н6	AUX+B	I/O	positive differential signal for AUX, port B
19	J6	AUX-B	I/O	negative differential signal for AUX, port B
23	Н9	AUX+A	I/O	positive differential signal for AUX, port A
24	J9	AUX-A	I/O	negative differential signal for AUX, port A
22	G8	GND	Ground	Ground
26	F8	D3+B	I/O	positive differential signal 3 for portB
27	F9	D3-B	I/O	negative differential signal 3 for portB
28	E8	D2+B	I/O	positive differential signal 2 for portB
29	E9	D2-B	I/O	negative differential signal 2 for portB
30	D8	D1+B	I/O	positive differential signal 1 for portB
31	D9	D1-B	I/O	negative differential signal 1 for portB
32	B8	D0+B	I/O	positive differential signal 0 for portB (Continued



42ZHE pin#	48NEE pin#	pin Name	Signal Type	Description
33	В9	D0-B	I/O	negative differential signal 0 for portB
35	A8	D3+A	I/O	positive differential signal 3 for port A
36	A9	D3-A	I/O	negative differential signal 3 for port A
	H4	GND	Ground	
37	В6	D2+A	I/O	positive differential signal 2 for port A
38	A6	D2-A	I/O	negative differential signal 2 for port A
39	B5	D1+A	I/O	positive differential signal 1 for port A
40	A5	D1-A	I/O	negative differential signal 1 for port A
41	B4	D0+A	I/O	positive differential signal 0 for port A
42	A4	D0-A	I/O	negative differential signal 0 for port A
21	A2	VDD	Pwr	Power
34		VDD	Pwr	Power
N/A	C2	DDC_ AUX_SEL	I	toggles between passing DDC channels through or AUX channels through If HIGH, then path DDC signals are passed through (depending on port selection via GPU_SEL) If LOW, then path AUX signals are passed through (depending on port selection via GPU_SEL)
5	N/A	AUX_HPD_ SEL	I	switches only the AUX and HPD channels from port A vs. port B
N/A	H5	SCL_B	I/O	DDC_clock channel for port B
N/A	H7	GND	Ground	
N/A	Н8	SCL_A	I/O	DDC_clock channel for port A
N/A	J5	SDA_B	I/O	DDC_data channel for port B
N/A	J8	SDA_A	I/O	DDC_data channel for port A
25	B7	OE	I	Output enable. if OE is high, IC is enabled. If OE is low, then IC is power down and all I/Os are hi-z
43	N/A	Center pad	Ground	Ground



### **Maximum Ratings**

(Above which useful life may be impaired. For user guidelines, not tested.) Note: Stresses greater than those listed under MAXI-

Storage Temperature	65°C to +150°C
Supply Voltage to Ground Potential	
DC Input Voltage	0.5V to V <sub>DD</sub>
DC Output Current	120mA
Power Dissipation	0.5W

Note: Stresses greater than those listed under MAXI-MUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

# DC Electrical Characteristics for Switching over Operating Range ( $T_A = -40^{\circ}\text{C}$ to $+105^{\circ}\text{C}$ , $V_{DD} = 3.3 \text{V} \pm 10\%$ )

Parameter	Description	Test Conditions(1)	Min	Typ <sup>(2)</sup>	Max	Units
V <sub>IH</sub>	Input HIGH Voltage	Guaranteed HIGH level	1.5			
VIL	Input LOW Voltage	Guaranteed LOW level			0.75	$\frac{1}{V}$
V <sub>IK</sub>	Clamp Diode Voltage (HS Channel)	$V_{\mathrm{DD}} = \mathrm{Max.},  \mathrm{I_{\mathrm{IN}}} = -18 \mathrm{mA}$		-1.6V	-1.8	V
VIK	Clamp Diode Voltage (Aux, Cntrl )	$V_{\mathrm{DD}} = \mathrm{Max.}$ , $I_{\mathrm{IN}} = -18\mathrm{mA}$		-0.7	-1.5	
IIH	Input HIGH Current	$V_{DD} = Max., V_{IN} = V_{DD}$			±5	
I <sub>IL</sub>	Input LOW Current	$V_{DD} = Max., V_{IN} = GND$			±5	μΑ
I <sub>OFF_SB</sub>	I/O leakage when part is off for sideband signals only (DDC, AUX, HPD)	$V_{DD} = 0V$ , $V_{INPUT} = 0V$ to 3.6V	20			
R <sub>ON_HS</sub>	On resistance between input to output for high speed signals	$V_{DD}$ = 3.0V, Vinput = -0.35V to 2V, $I_{INPUT}$ = 20mA		10.0		Ohm
R <sub>ON_AUX</sub>	On resistance between input to output for side-band signals (AUX)	$V_{DD}$ = 3.0V, Vinput = 0 to 3.3V, $I_{INPUT}$ = 20mA		7		Ohm
R <sub>ON_DDC</sub>	On resistance between input to output for DDC channel	$V_{DD} = 3.0V$ , $V_{IINPUT} = 0V$ , $I_{INPUT} = 20$ mA		10		Ohm
Aux_ss	Signal Swing Tolerance in Aux path	$V_{\mathrm{DD}} = 3.0 \mathrm{V}$	-0.5		3.6	V
HPD_I	Input voltage on HPD path				5.5	V
HPD_O	Output voltage tolerance on HPD path	HPD input from 3.3V to 5.25V		3.3	3.6	V

# Power Supply Characteristics ( $T_A = -40^{\circ}\text{C} \text{ to } +105^{\circ}\text{C}$ )

Parameter	Description	Test Conditions <sup>(1)</sup>	Min	Typ <sup>(2)</sup>	Max	Units
$I_{\mathrm{DD}}$	Power Supply Current	$V_{DD}$ = 3.3V, OE = 3.3V, $V_{IN}$ = GND or $V_{DD}$		0.4	1	mA
$I_{\mathrm{DDQ}}$	Quiescent Power Supply Current	$V_{DD} = 3.3V$ , OE = GND		1		μΑ

<sup>1.</sup> For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.

<sup>2.</sup> Typical values are at  $V_{DD}$  = 3.3V,  $T_A$  = 25°C ambient and maximum loading.



# **Dynamic Electrical Characteristics over Operating Range** ( $T_A = -40^{\circ}$ to $+105^{\circ}$ C, $V_{DD} = 3.3$ V $\pm 10\%$ )

Param- eter	Description	Test Conditions <sup>1</sup>		Min	Typ <sup>2</sup>	MAX	Units
V	Crosstalk on High Speed Chan-	See Fig. 1 for Measure-	f= 2.7 GHz		-28	-25	
$X_{TALK}$	nels	ment Setup	f = 1.35 GHz		-32	-28	
0	OFF Isolation on High Speed	See Fig. 2 for Measurement Setup,	f= 2.7 GHz		-22	-20	dB
O <sub>IRR</sub> Channels	Channels	ment Setup,	f = 1.35 GHz		-30	-27	
т	Differential Insertion Loss on		TQFN package	-1.8	-1.6		1D
I <sub>LOSS</sub> High Speed Channels	High Speed Channels	@5.4Gbps (see figure 3)	BGA package	-2.0	-1.8		dB
Differential Return Loss on	Differential Return Loss on high		TQFN package		-16.0	-14	- dB
R <sub>loss</sub>	speed channels	@ 2.7GHz (5.4Gbps)	BGA package		-14	-12.5	
DIA D	Bandwidth -3dB for Main high		TQFN package	4.1	4.6		GHz
BW_Dx±	speed path (Dx±)	See figure 3	BGA package	3.7	4.1		
BW_AUX/ HPD	-3dB BW for AUX and HPD signals	See figure 3		1.35	1.5		GHz
Tsw a-b	time it takes to switch from port A to port B					1	us
Tsw b-a	time it takes to switch from port B to port A					1	us
Tstartup	V <sub>DD</sub> valid to channel enable					10	us
Twakeup	Enabling output by changing OE from low to High					10	us

<sup>1.</sup> For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.

# Switching Characteristics (TA= -40° to +105°C, $V_{DD}=3.3V\pm10\%$ )

Parameter	Description	Min.	Тур.	Max.	Units
$T_{pd}$	Propagation delay (input pin to output pin) on all channels		80		ps
t <sub>b-b</sub>	Bit-to-bit skew within the same differential pair of Dx± channels		5	7	ps
t <sub>ch-ch</sub>	Channel-to-channel skew of Dx± channels			35	ps

<sup>2.</sup> Typical values are at  $V_{\rm DD}$  = 3.3V,  $T_{\rm A}$  = 25°C ambient and maximum loading.



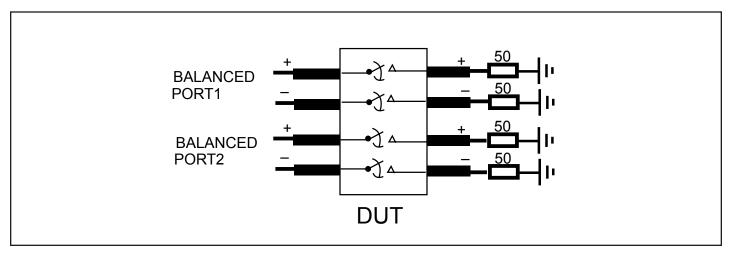


Fig 1. Crosstalk Setup

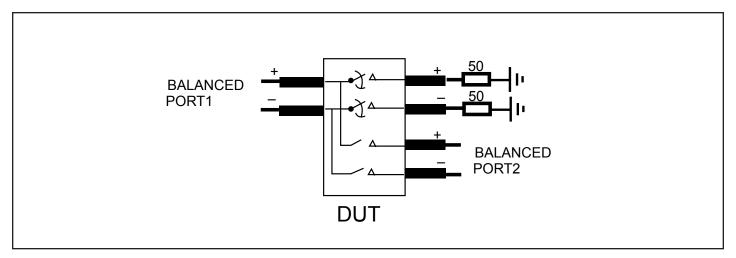


Fig 2. Off-isolation setup

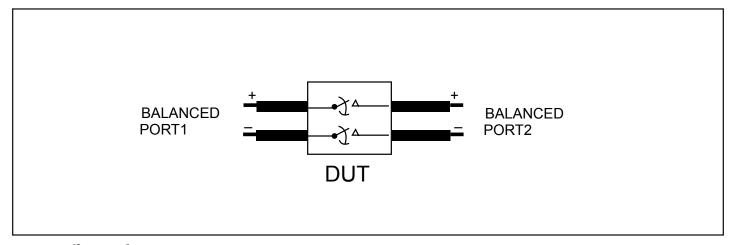
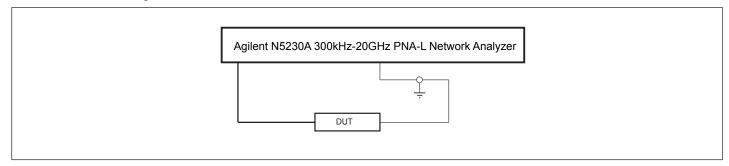


Fig 3. Differential Insertion Loss



# **Test Circuit for Dynamic Electrical Characteristics**



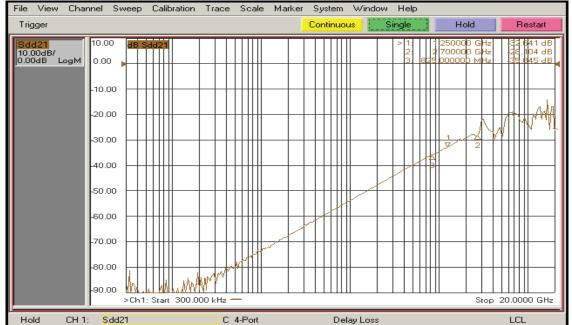


Fig 4. Crosstalk

12-0293 8 12/17/12



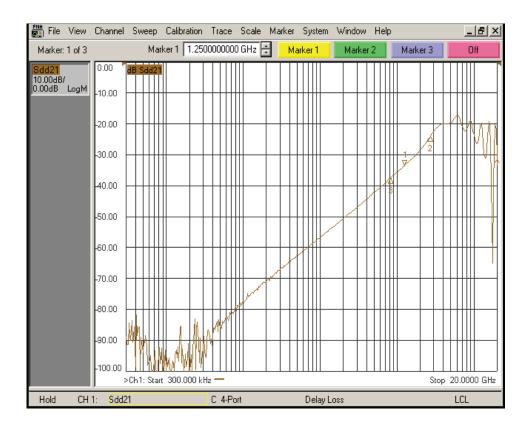


Fig 5. Off Isolation

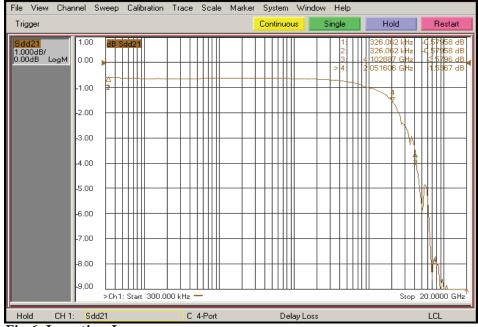
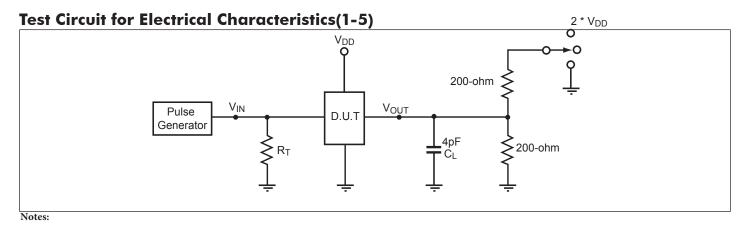


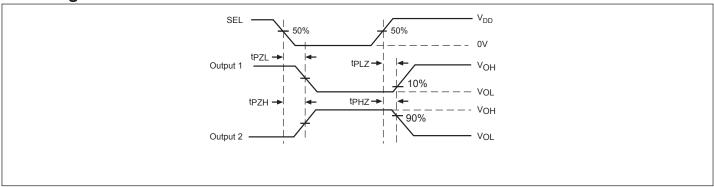
Fig 6. Insertion Loss





- 1.  $C_L$  = Load capacitance: includes jig and probe capacitance.
- 2.  $R_T$  = Termination resistance: should be equal to  $Z_{OUT}$  of the Pulse Generator
- 3. Output 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- 4. Output 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- 5. All input impulses are supplied by generators having the following characteristics:  $PRR \le MHz$ ,  $Z_O = 50\Omega$ ,  $t_R \le 2.5ns$ ,  $t_F \le 2.5ns$ .
- 6. The outputs are measured one at a time with one transition per measurement.

### **Switching Waveforms**

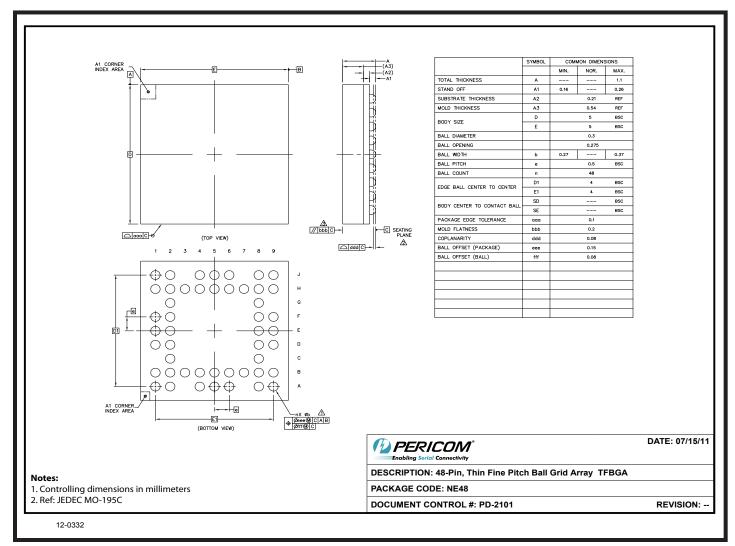


#### **Voltage Waveforms Enable and Disable Times**

### **Switch Positions**

Test	Switch
t <sub>PLZ</sub> , t <sub>PZL</sub> (output on B-side)	2*V <sub>DD</sub>
t <sub>PHZ</sub> , t <sub>PZH</sub> (output on B-side)	GND
Prop Delay	Open

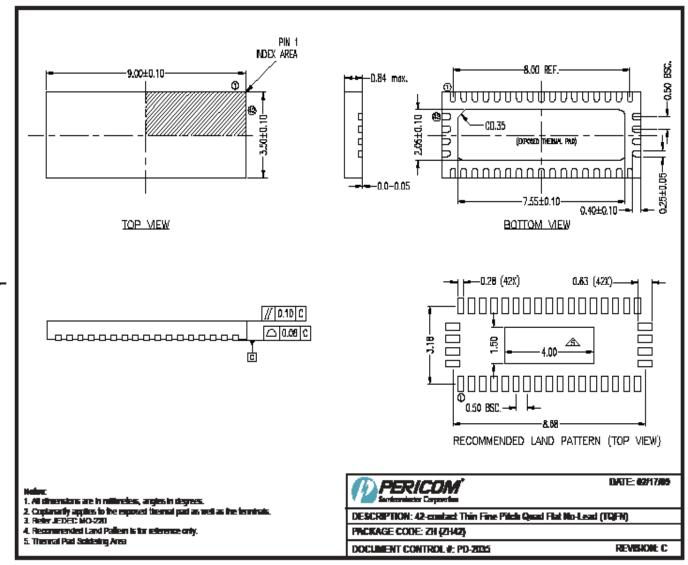




#### Note:

For latest package info, please check: http://www.pericom.com/products/packaging/mechanicals.php





**09-**01 16

#### Note:

For latest package info, please check: http://www.pericom.com/products/packaging/mechanicals.php

## **Ordering Information**

Ordering Code	Package Code	Package Description
PI3VDP12412ZHE	ZH	Pb-free & Green, 42-contact TQFN
PI3VDP12412NEE	NE	Pb-free & Green, 48-ball BGA

#### Notes

- $\bullet \ \ Thermal\ characteristics\ can\ be\ found\ on\ the\ company\ web\ site\ at\ www.pericom.com/packaging/$
- "E" denotes Pb-free and Green
- Adding an "X" at the end of the ordering code denotes tape and reel packaging